


TotalEnergies

Refining & Chemicals
Polymers

Polyethylene MS482

Technical data sheet
High Density Polyethylene FUEL SYSTEMS
Produced in Europe

Description

MS482 is a high density polyethylene resin with excellent Environmental Stress Cracking Resistance (ESCR) intended for the injection moulding of automotive components such as DEF (AdBlue®) tanks for Selective Catalytic Reduction (SCR) systems.

MS482 combines high performance with easy processing and good dimensional stability.

MS482 is a pellet grade and contains antioxidants.

Characteristics

Property	Method	Unit	Typical value (*)
Density	ISO 1183	g/cm ³	0.947
Melt Flow Rate (190°C/2.16 kg)	ISO 1133/D	g/10 min	2
Melt Flow Rate (190°C/21.6 kg)	ISO 1133/G	g/10 min	80
Tensile Modulus	ISO 527	MPa	900
Tensile Strength at Yield	ISO 527	MPa	23
ESCR AntaroX 100% F ₅₀	ASTM D 1693	h	> 1000

(*) Data not intended for specification purposes

Processing

It is recommended to process MS482 within the temperature range 180-240°C.

Handling and storage

Please refer to the safety data sheet (SDS) for handling and storage information. It is advisable to convert the product within one year after delivery provided storage conditions are used as given in the SDS of our product. SDS may be obtained from the website: www.polymers.totalenergies.com.

Polyethylene

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